



Material Composition

Package : LGA 1.45x1.45
 Part No : RR123-1H02-612
 Total Pck Weigt 2.15mg

Name		Composition	CAS NO.	%	mg(ave)	mg	%	PPM		
Wafer	Silicon	Silicon	7440-21-3	100%	0.21500	0.2150	9.991%	99,907		
Substrate	BT NiAu	Copper (Cu)	7440-50-8	48.00%	0.30960	0.6450	29.972%	299,721		
		BT material : Cured thermosetting resin / inorganic filler / Continuous Filament Fiber Glass	65997-17-3 / NA	40.00%	0.25800				14.387%	143,866
		Solder mask (cured)	14807-96-6 / 7727-43-7	5.00%	0.03225				1.499%	14,986
		Nickel (Ni)	7440-02-0	5.00%	0.03225				1.499%	14,986
		Gold (Au)	7440-57-5	2.00%	0.01290				0.599%	5,994
Die attach	DAF ATB-F125E	Silicon dioxide	7631-86-9	56.00%	0.06020	0.1075	4.995%	49,954		
		Butadiene, acrylonitrile polymer, carboxy-terminated, polymer with bisphenol A and epichlorhydrin	68610-41-3	26.00%	0.02795				1.299%	12,988
		Poly[oxy[(2-oxiranyl)-1,2-cyclohexanediy]], a-hydro-w-hydroxy-, ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1)	244772-00-7	6.00%	0.00645				0.300%	2,997
		Phenol-formaldehyde polymer	9003-35-4	6.00%	0.00645				0.300%	2,997
		reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6	6.00%	0.00645				0.300%	2,997
Wire	Au	Gold	7440-57-5	99.0000%	0.06386	0.0645	2.997%	29,972		
		Beryllium	7440-05-3	0.9980%	0.00064				0.030%	299
		Calcuim	7440-70-2	0.0020%	0.00000				0.000%	1
Mold compound	EME-G770H	Epoxy resin	Trade Secret	10.00%	0.11200	1.1200	52.045%	520,446		
		Phenol Resin	Trade Secret	4.50%	0.05040				2.342%	23,420
		Silica(Amorphous)	60676-86-0	80.00%	0.89600				41.636%	416,357
		Silicone Elastomer	Trade Secret	4.50%	0.05040				2.342%	23,420
		Carbon black	1333-86-4	1.00%	0.01120				0.520%	5,204
		Total								